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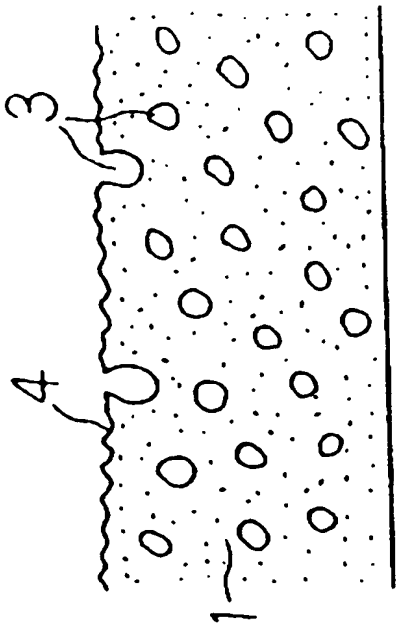
TITLE : MIRROR POLISHING METHOD FOR SEMICONDUCTOR WAFER



ABSTRACT : PURPOSE: To decrease flaw generated at the time of polishing a wafer improved in finished surface flatness by using a trued urethane pad as the polishing pad. CONSTITUTION: A polishing pad is combined with a polishing material containing abrasive grains and etchant, polishing a mirror surface of a semiconductor wafer. Here smoothly flatting by truing a surface 4 of a urethane pad, formed by a polyurethane sheet with most of the blow holes 3 closed, the urethane pad is used as the polishing pad. Thus by using the urethane pad applying truing, polished surface roughness of the semiconductor wafer decreases, and flaw generated at the time of polishing the wafer, decreases while improving flatness.